

#10 / 9/5/01
Docket No. 66286-002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Tai-Chong CHAI et al.

Serial No.: 09/497,421

Filed: February 7, 2000

Date: August 16, 2001

Art Unit: 2815

Examiner: L. Cruz

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Technology Center 2100

For: LEAD FRAME FOR AN INTEGRATED CIRCUIT CHIP (SMALL WINDOW)

Commissioner for Patents
Washington, D.C. 20231

Sir:

**INFORMATION DISCLOSURE STATEMENT
AND PETITION FOR CONSIDERATION THEREOF
35 U.S.C. §6; 37 C.F.R. §§1.56, 1.97 and 1.98**

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Applicants bring to the attention of the United States Patent and Trademark Office the reference listed on the attached appendix and on the attached Form PTO-1449. Unless otherwise indicated, a copy of the reference is attached. The Applicants respectfully request that this information submitted be considered during the prosecution of this Application and that the reference be made of record and appear among the "References Cited" on any patent that may issue from the above-identified Application.

This Information Disclosure Statement is filed more than three months after the U.S. filing date AND after the mailing date of the first Office Action on the merits, but before the mailing date of a Final Rejection or Notice of Allowance.

The Applicants petition the United States Patent and Trademark Office to consider this Information Disclosure Statement, under 37 C.F.R. §1.97(d)(2).

No significance should be drawn from markings occurring on the document submitted herewith.

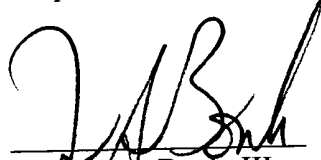
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This paper was not filed within the shortened statutorily-prescribed time limit, thus incorporates a petition and is accompanied by the required fee. The undersigned authorizes the Commissioner to deduct \$180 to cover the fee set forth under 37 C.F.R. §1.17(i), and such additional fees as necessary for filing this or accompanying papers, from Deposit Account No. 04-2223.

Respectfully Submitted,

A handwritten signature in black ink, appearing to read 'W. A. Bonk, III', written over a horizontal line.

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APPENDIX

1. United States Patent No. 5,543,657, issued August 6, 1996, to S.J. Diffenderfer et al., entitled *Single Layer Leadframe Design With Groundplane Capability*.